3A SURFACE MOUNT SCHOTTKY BRIDGE

Reverse Voltage - 60 V Forward Current - 3.0A

Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- · High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications
- Hireliability application and automotive grade AEC-Q101 qualified

MECHANICAL DATA

· Case: ABS/LBF

• Terminals: Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 88mg 0.0031oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

3 4 2 ABS/LBF Package
Automotive Grade

DESCRIPTION

Input Pin (~)

Input Pin (~)

Output Anode (+)

Output Cathode (-)

PINNING

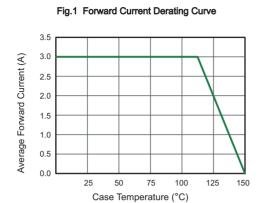
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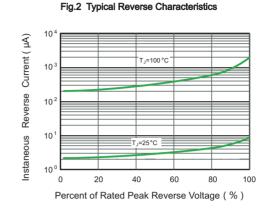
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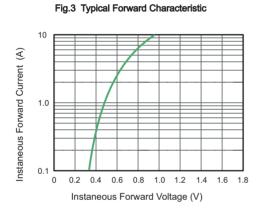
Parameter	Symbols	AT-TB36SM	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	60	V
Maximum RMS voltage	V _{RMS}	42	V
Maximum DC Blocking Voltage	V _{DC}	60	V
Maximum Average Forward Rectified Current @ Fig.1	I _{F(AV)}	3.0	А
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	80	Α
Peak Forward Surge Current,1.0ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	160	А
I ² t Rating for fusing (3ms≤t≤8.3ms)	l²t	26.6	A ² S
Max Instantaneous Forward Voltage at 3A	V _F	0.66	V
Maximum DC Reverse Current $T_a = 25^{\circ}$ C at Rated DC Reverse Voltage $T_a = 100^{\circ}$ C	I _R	0.02 2.5	mA
Typical Junction Capacitance (1)	C _j	110	pF
Typical Thermal Resistance (2)	R _{0JA} R _{0JC} R _{0JL}	40 8 20	°C/W
Operating Junction Temperature Range	Tj	-55 ~ + 150	°C
Storage Temperature Range	T_{stg}	-55 ~ + 150	°C

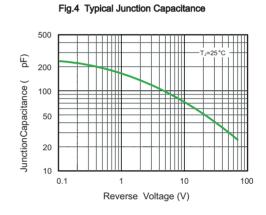
⁽¹⁾ Measured at 1 MHz and applied reverse voltage of 4 V D.C

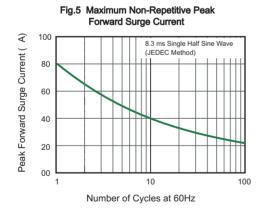
⁽ 2) P.C.B. mounted with 4X1.5" X 1.5" (3.81 X 3.81cm) copper pad areas.







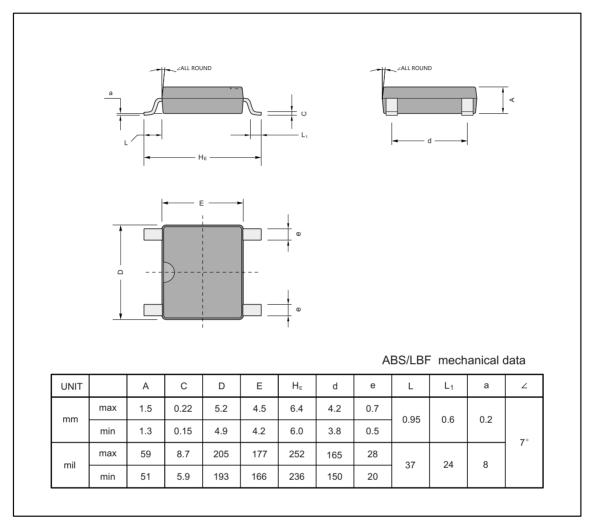




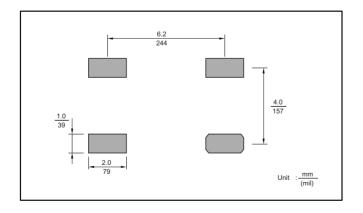
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

ABS/LBF



The recommended mounting pad size



Marking

Type number	Marking code
AT-TB36SM	TB36S

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